

FIG. 1

100

110 Providing a substrate supporting a plurality of devices, each having a flip-chip interconnect

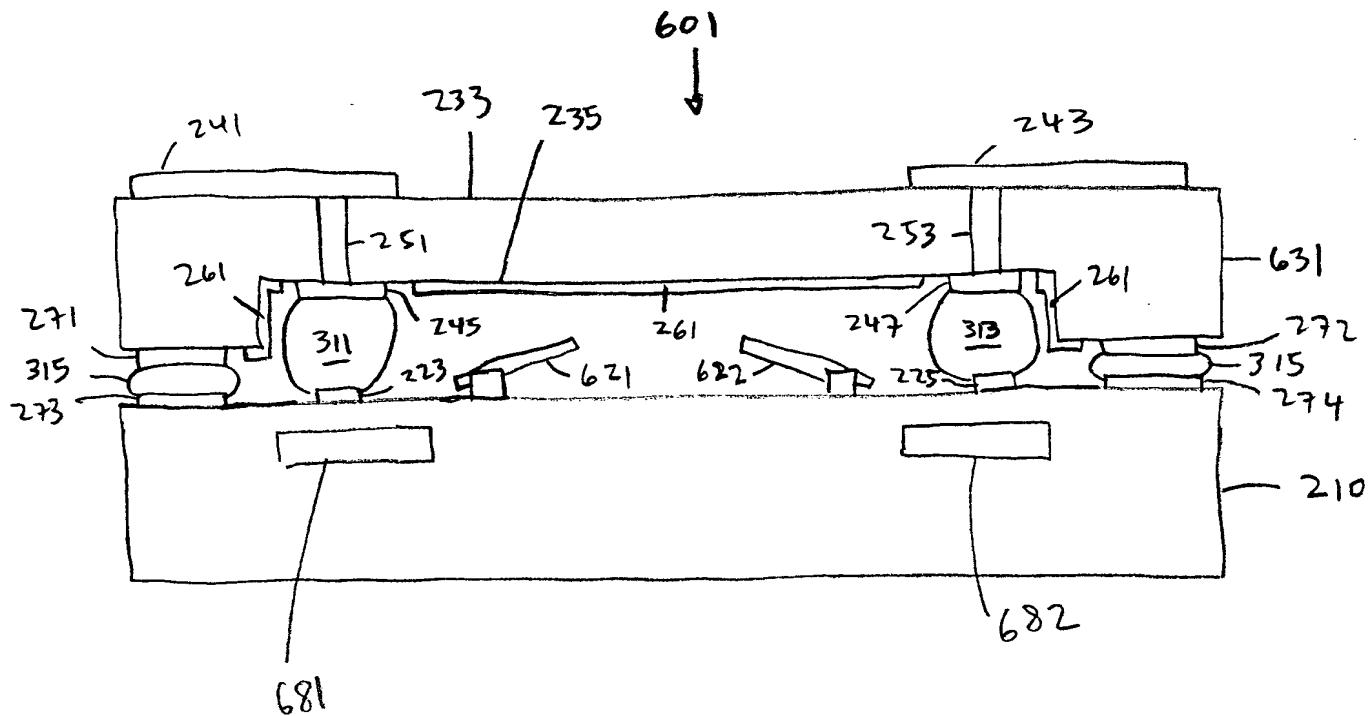
↓

120 Packaging the plurality of devices while the substrate remains whole

↓

130 Singulating the plurality of devices

FIG. 6



216

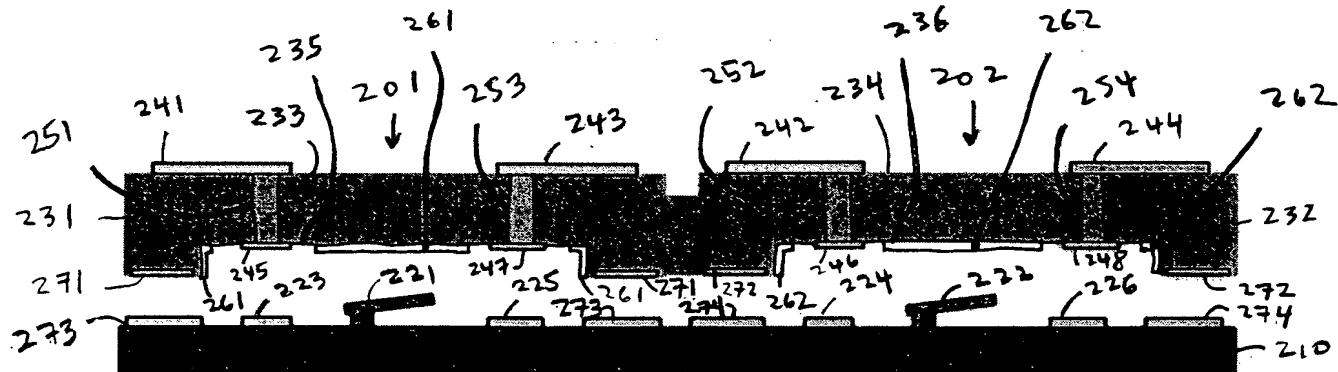


FIG. 2

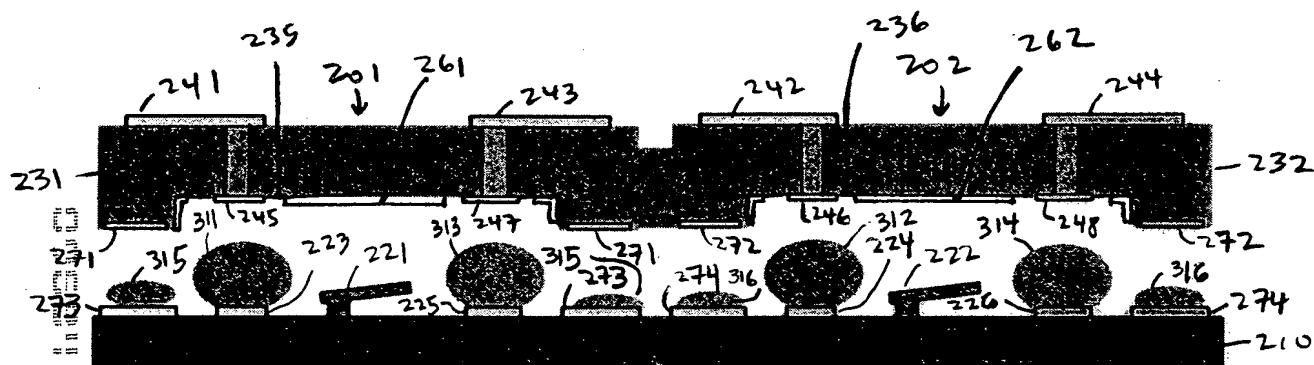
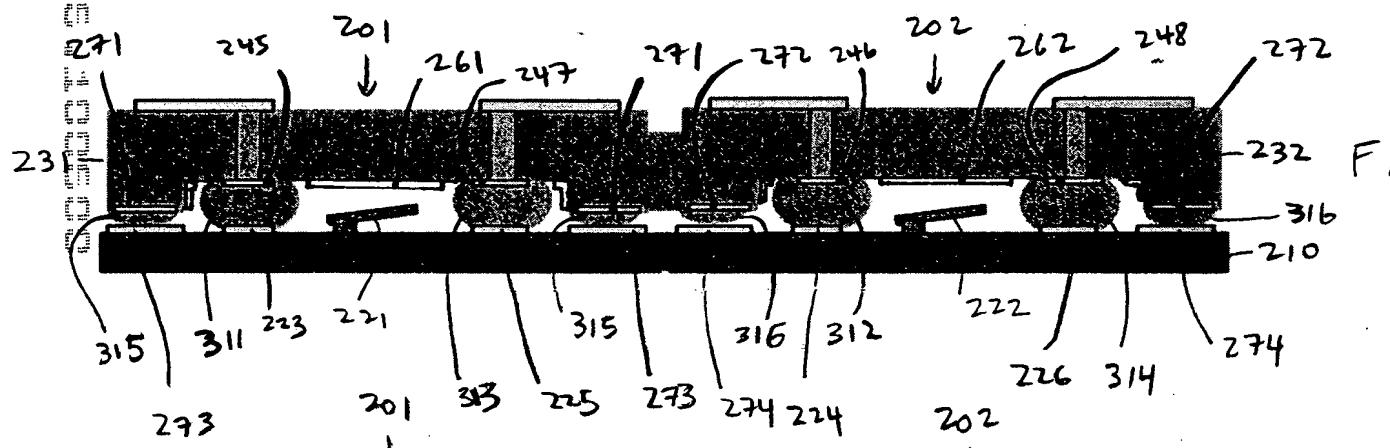


FIG. 3



- FIG. 4

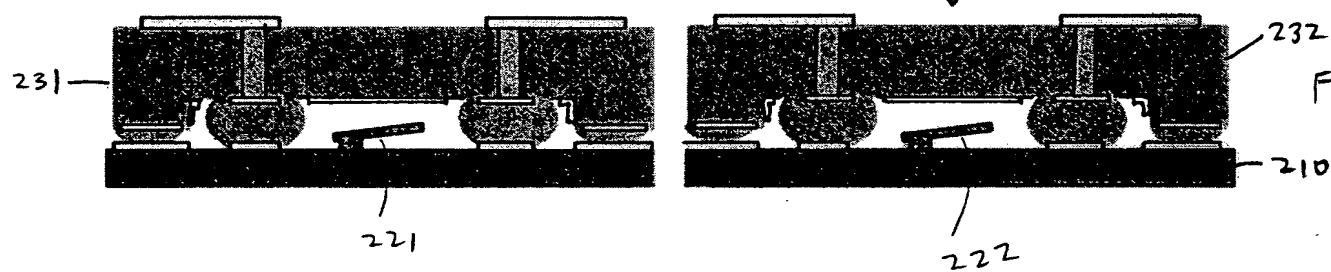
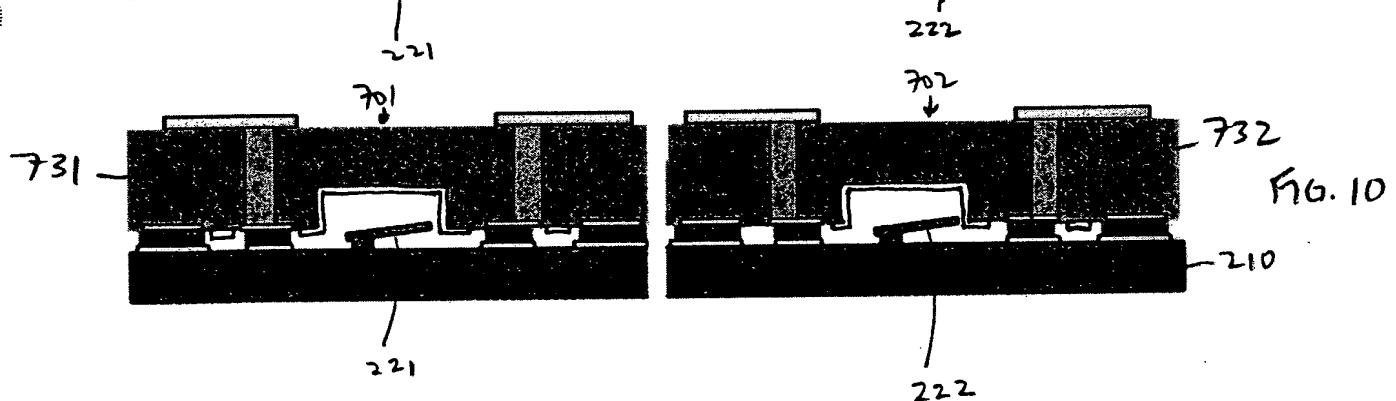
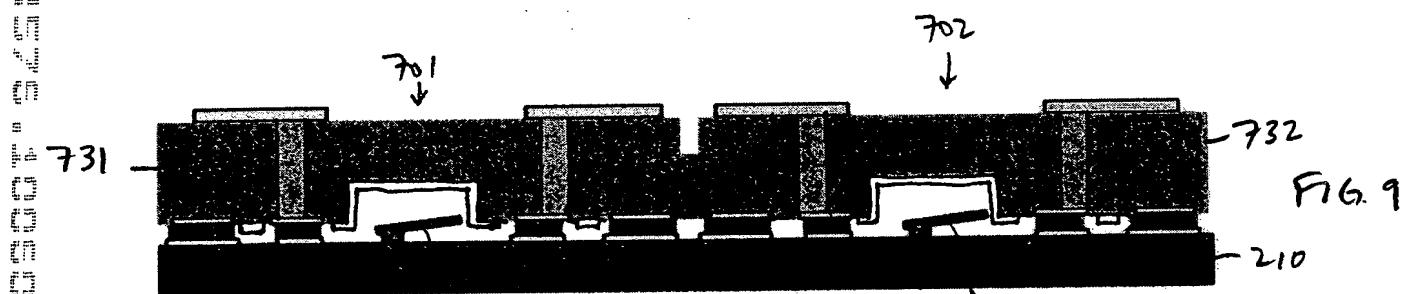
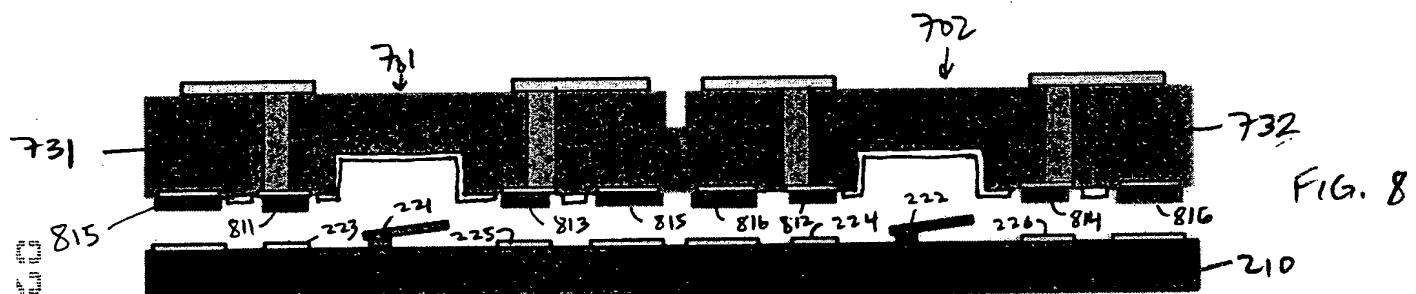
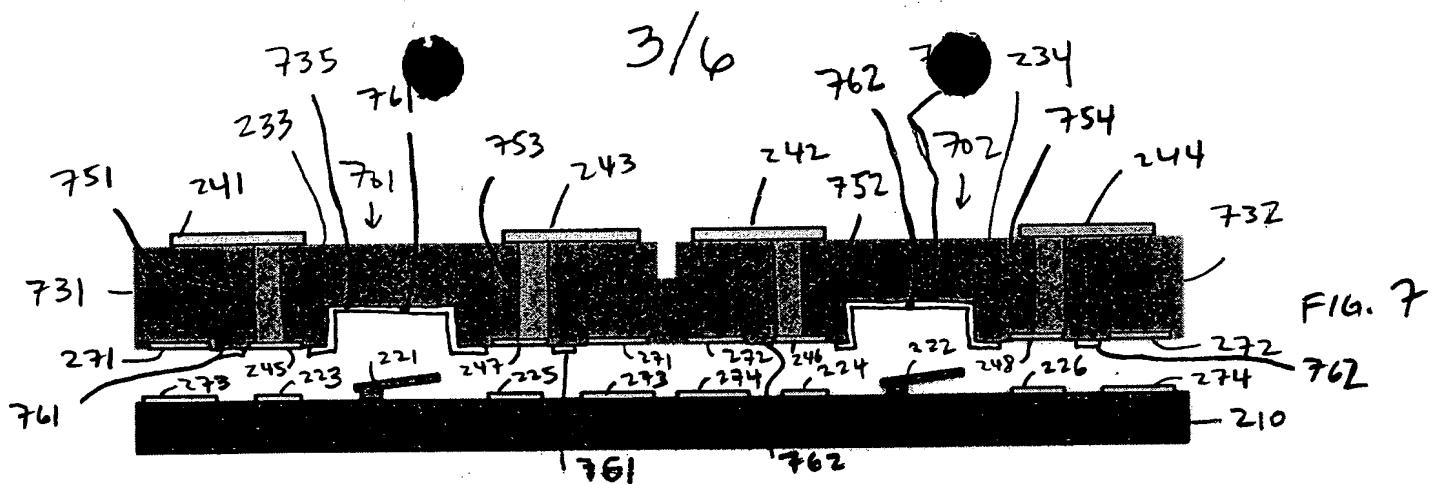


FIG. 5



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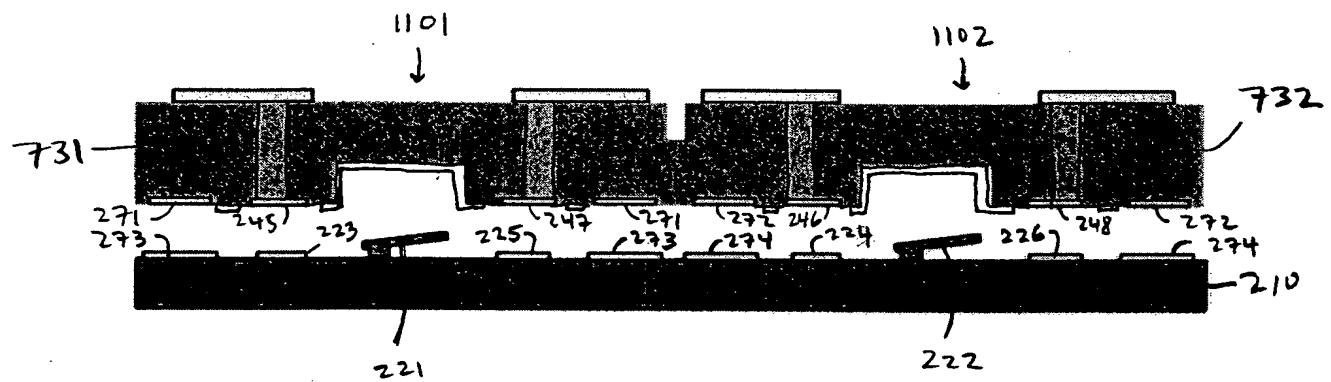


FIG. II

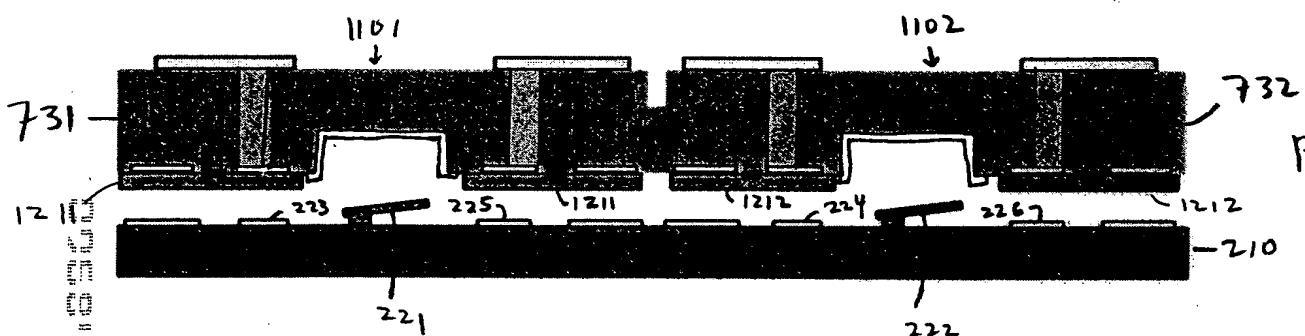


FIG. 12

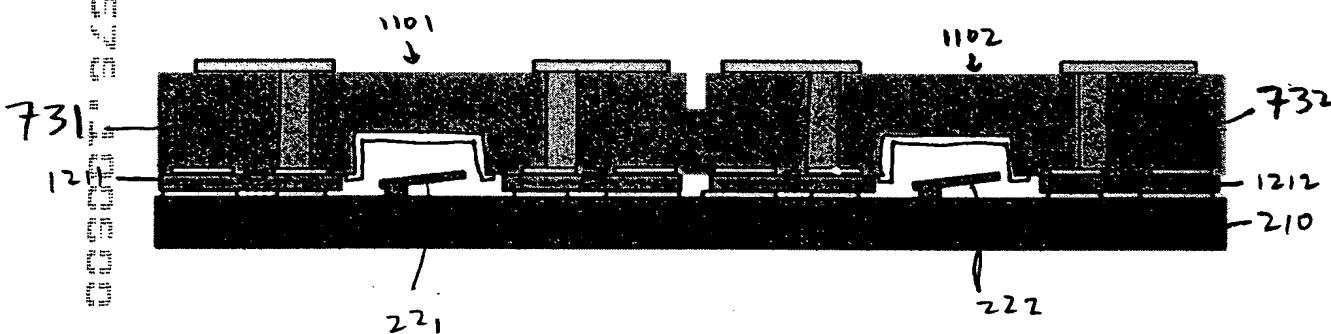


FIG. 13

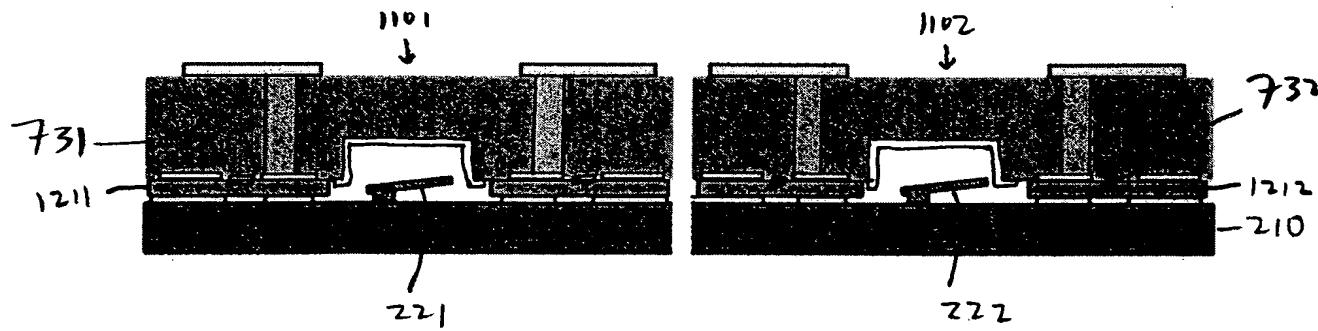


Fig. 14

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